



--	--	--	--	--	--

A 202



PDFN5×6 N
N-Channel MOSFET in a PDFN5×6 Plastic Package .

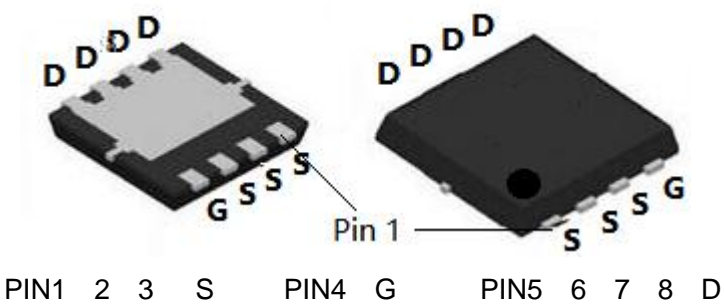
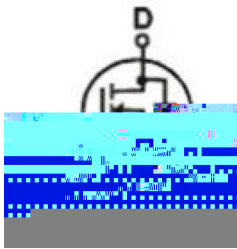
Low $R_{DS(ON)}$ to minimize conductive loss;low Gate Charge for fast switching;Low Thermal resistance;HF Product.

MB/NB/UMPC/VGA

Buck

-

Battery Management,High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA,Networking DC-DC Power System,Load Switch.



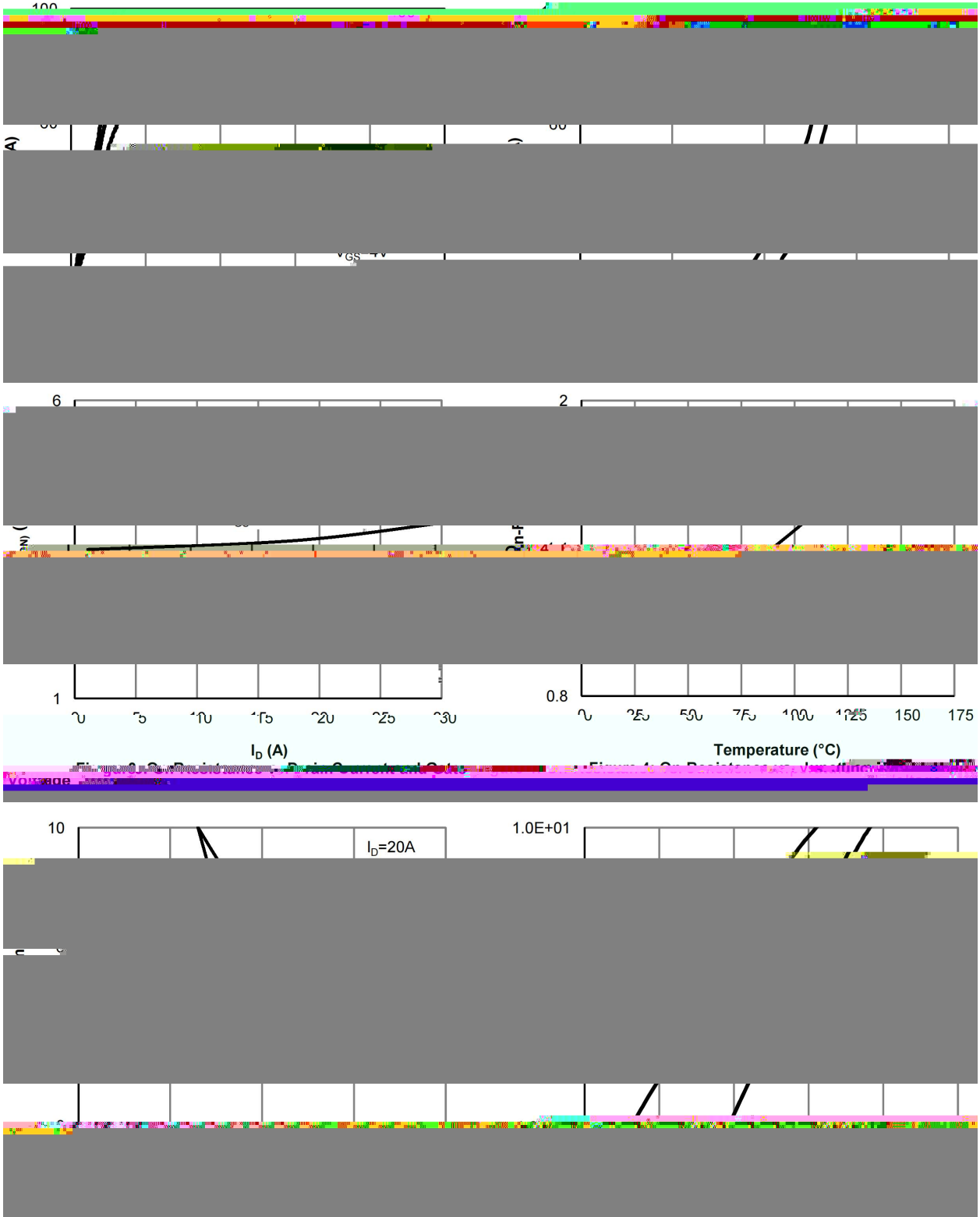
See Marking Instructions.



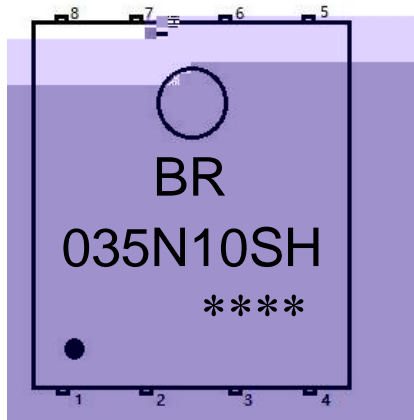
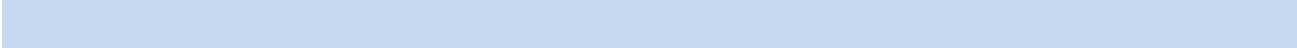
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Drain Current - Continuous	I_D	168	A
Drain Current – Pulsed	I_{DM}	400	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	$P_D(T_c=25^\circ\text{C})$	215	W
Single Pulse Avalanche Energy(L=0.5mH)	E_{AS}	563	mJ
Avalanche Current(L=0.5mH)	I_{AS}	37.5	A
Junction and Storage Temperature Range	T_j, T_{stg}	-55 to 150	$^\circ\text{C}$
Thermal resistance, junction - ambient $t \leq 10\text{s}$	R_{JA}		



Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $R_L=2.5\ \Omega$				
		$V_{DS}=50V$ $R_{GEN}=3\ \Omega$				







BR

035N10SH

Note

BR

Company Code

035N10SH

Product Type

****:

Lot No. Code, code change with Lot No



Temperature Profile for IR Reflow Soldering(Pb-Free)

- | | | | | | | |
|---|-------|-----|----|-----------|-------|--|
| 1 | 150 | 180 | 60 | 90sec; | Note: | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec